

AO3403

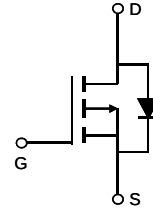
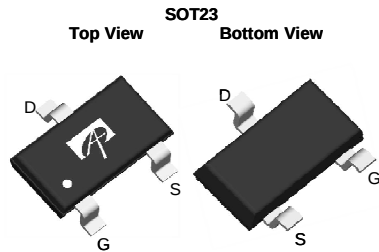
30V P-Channel MOSFET

General Description

The AO3403 uses advanced trench technology to provide excellent $R_{DS(ON)}$ and low gate charge. This device is suitable for use as a load switch or in PWM applications.

Product Summary

V_{DS}	-30V
I_D (at $V_{GS} = -10V$)	-2.6A
$R_{DS(ON)}$ (at $V_{GS} = -10V$)	< 115m Ω
$R_{DS(ON)}$ (at $V_{GS} = -4.5V$)	< 150m Ω
$R_{DS(ON)}$ (at $V_{GS} = -2.5V$)	< 200m Ω



Absolute Maximum Ratings $T_A = 25^\circ\text{C}$ unless otherwise noted

Parameter	Symbol	Maximum	Units
Drain-Source Voltage	V_{DS}	-30	V
Gate-Source Voltage	V_{GS}	± 12	V
Continuous Drain Current	I_D	-2.6	A
$T_A = 25^\circ\text{C}$		-2.2	
$T_A = 70^\circ\text{C}$			
Pulsed Drain Current ^C	I_{DM}	-13	
Power Dissipation ^B	P_D	1.4	W
$T_A = 25^\circ\text{C}$		0.9	
$T_A = 70^\circ\text{C}$			
Junction and Storage Temperature Range	T_J, T_{STG}	-55 to 150	$^\circ\text{C}$

Thermal Characteristics

Parameter	Symbol	Typ	Max	Units
Maximum Junction-to-Ambient ^A	$R_{\theta JA}$	70	90	$^\circ\text{C/W}$
$t \leq 10\text{s}$				
Maximum Junction-to-Ambient ^{A,D}	$R_{\theta JA}$	100	125	$^\circ\text{C/W}$
Steady-State				
Maximum Junction-to-Lead	$R_{\theta JL}$	63	80	$^\circ\text{C/W}$
Steady-State				

Electrical Characteristics (T_j=25°C unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
STATIC PARAMETERS						
BV _{DSS}	Drain-Source Breakdown Voltage	I _D =-250μA, V _{GS} =0V	-30			V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =-30V, V _{GS} =0V T _j =55°C			-1 -5	μA
I _{GSS}	Gate-Body leakage current	V _{DS} =0V, V _{GS} = ±12V			±100	nA
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =-250μA	-0.6	-1	-1.4	V
I _{D(ON)}	On state drain current	V _{GS} =-10V, V _{DS} =-5V	-13			A
R _{DS(ON)}	Static Drain-Source On-Resistance	V _{GS} =-10V, I _D =-2.6A T _j =125°C		88 143	115 200	mΩ
		V _{GS} =-4.5V, I _D =-2A		103	150	mΩ
		V _{GS} =-2.5V, I _D =-1A		139	200	mΩ
g _{FS}	Forward Transconductance	V _{DS} =-5V, I _D =-2.6A		8		S
V _{SD}	Diode Forward Voltage	I _S =-1A, V _{GS} =0V		-0.78	-1	V
I _S	Maximum Body-Diode Continuous Current				-1.5	A
DYNAMIC PARAMETERS						
C _{iss}	Input Capacitance	V _{GS} =0V, V _{DS} =-15V, f=1MHz		260	315	pF
C _{oss}	Output Capacitance			37		pF
C _{rss}	Reverse Transfer Capacitance			20		pF
R _g	Gate resistance	V _{GS} =0V, V _{DS} =0V, f=1MHz	4	8	12	Ω
SWITCHING PARAMETERS						
Q _{g(10V)}	Total Gate Charge	V _{GS} =-10V, V _{DS} =-15V, I _D =-2.6A		5.9	7.2	nC
Q _{g(4.5V)}	Total Gate Charge			2.8	3.5	nC
Q _{gs}	Gate Source Charge			0.7		nC
Q _{gd}	Gate Drain Charge			1		nC
t _{D(on)}	Turn-On DelayTime	V _{GS} =-10V, V _{DS} =-15V, R _L =5.76Ω, R _{GEN} =3Ω		6		ns
t _r	Turn-On Rise Time			3.5		ns
t _{D(off)}	Turn-Off DelayTime			20		ns
t _f	Turn-Off Fall Time			5		ns
t _{rr}	Body Diode Reverse Recovery Time	I _F =-2.6A, dI/dt=100A/μs		11.5	15	ns
Q _{rr}	Body Diode Reverse Recovery Charge	I _F =-2.6A, dI/dt=100A/μs		4.5		nC

A. The value of R_{θJA} is measured with the device mounted on 1in² FR-4 board with 2oz. Copper, in a still air environment with T_A=25° C. The value in any given application depends on the user's specific board design.

B. The power dissipation P_D is based on T_{J(MAX)}=150° C, using ≤ 10s junction-to-ambient thermal resistance.

C. Repetitive rating, pulse width limited by junction temperature T_{J(MAX)}=150° C. Ratings are based on low frequency and duty cycles to keep initial T_J=25° C.

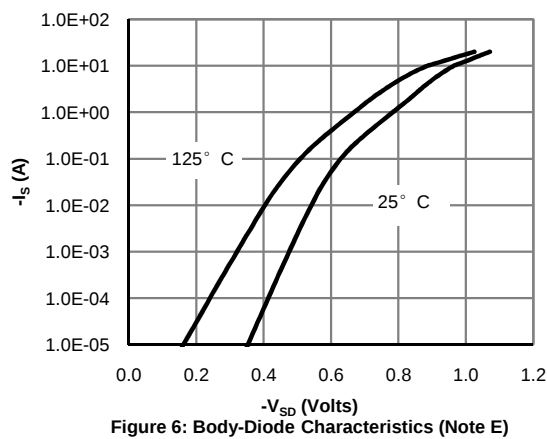
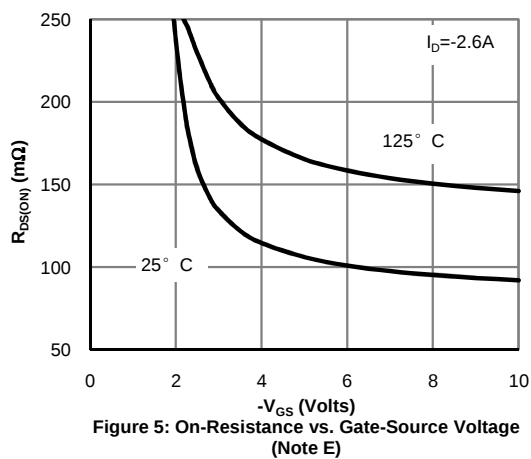
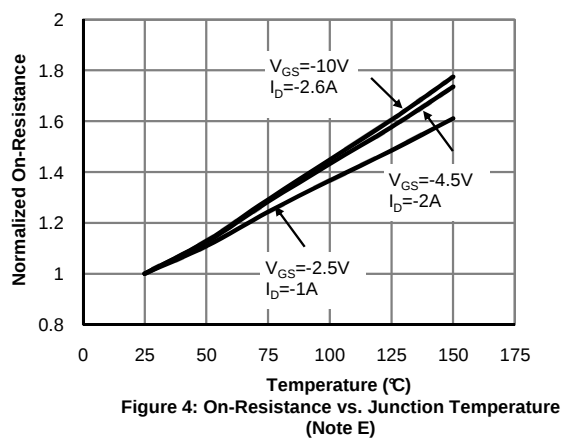
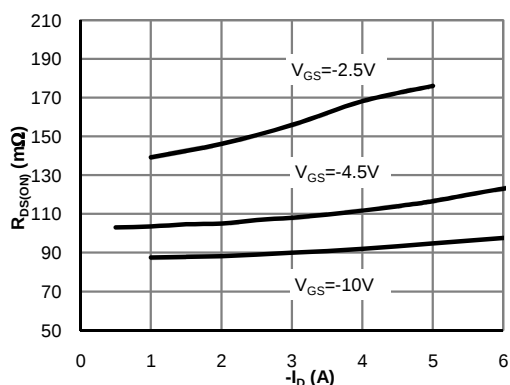
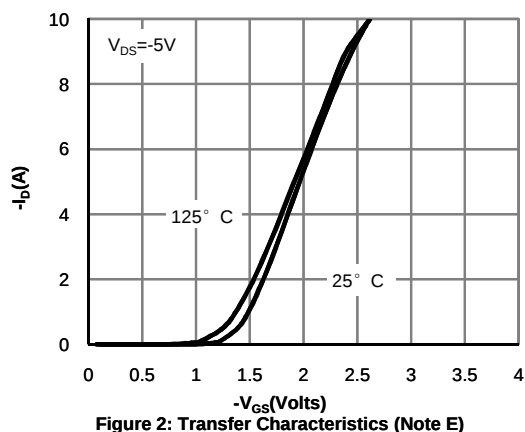
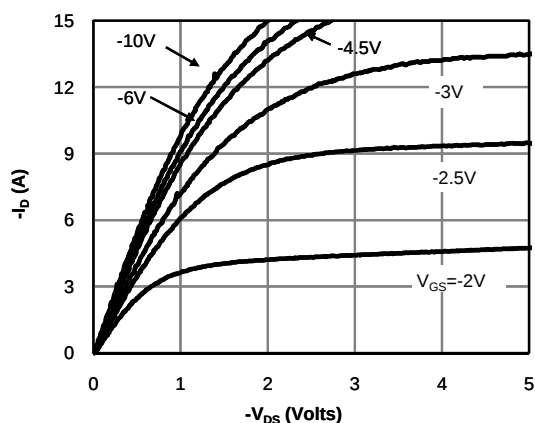
D. The R_{θJA} is the sum of the thermal impedance from junction to lead R_{θJL} and lead to ambient.

E. The static characteristics in Figures 1 to 6 are obtained using <300μs pulses, duty cycle 0.5% max.

F. These curves are based on the junction-to-ambient thermal impedance which is measured with the device mounted on 1in² FR-4 board with 2oz. Copper, assuming a maximum junction temperature of T_{J(MAX)}=150° C. The SOA curve provides a single pulse rating.

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TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS



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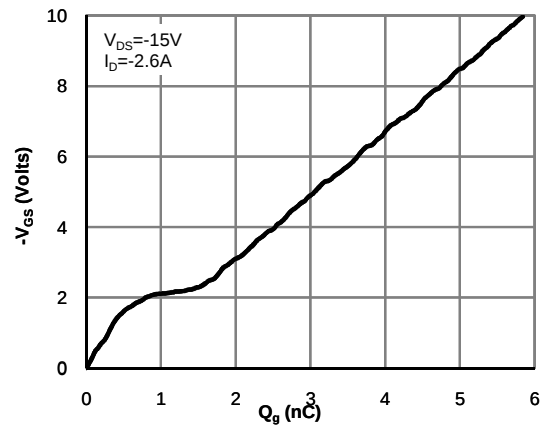


Figure 7: Gate-Charge Characteristics

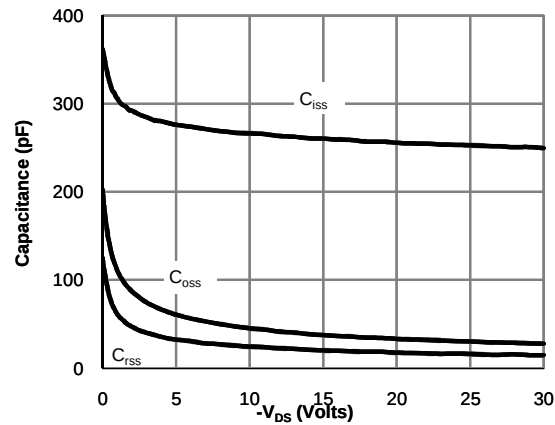


Figure 8: Capacitance Characteristics

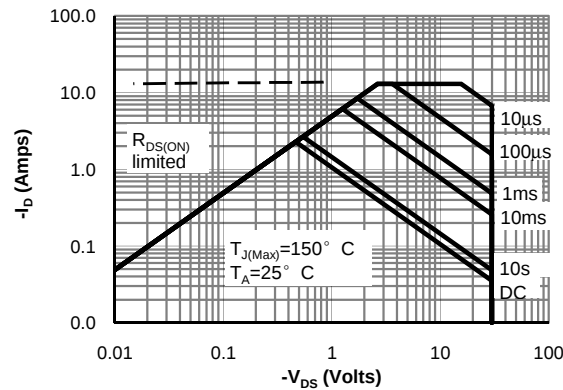


Figure 9: Maximum Forward Biased Safe Operating Area (Note F)

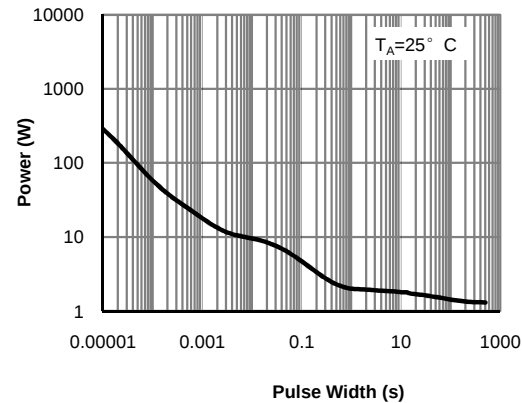


Figure 10: Single Pulse Power Rating Junction-to-Ambient (Note F)

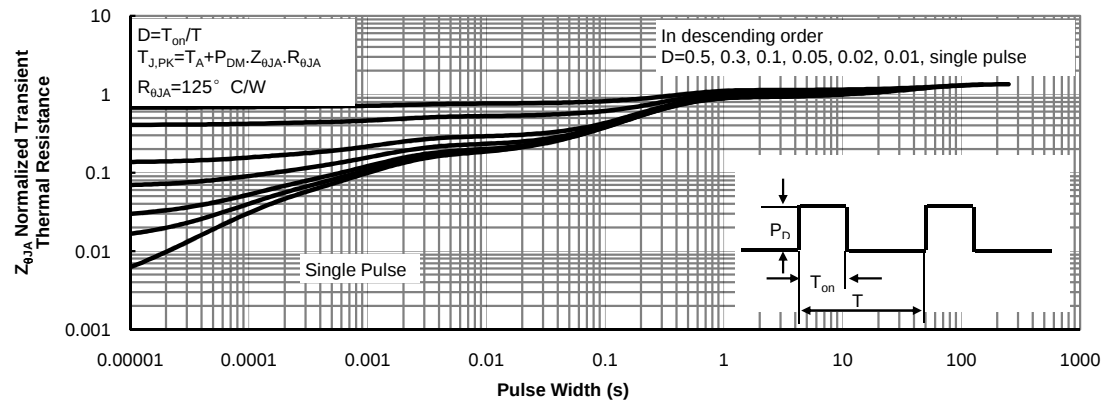
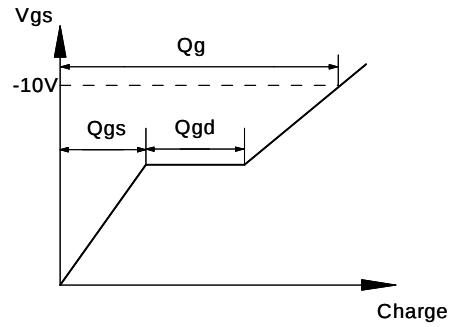
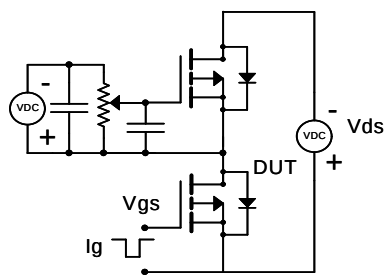
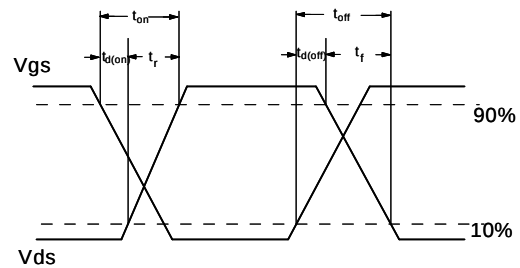
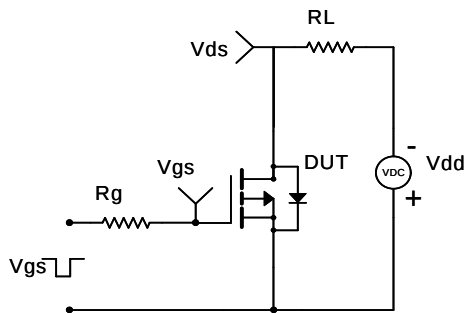


Figure 11: Normalized Maximum Transient Thermal Impedance (Note F)

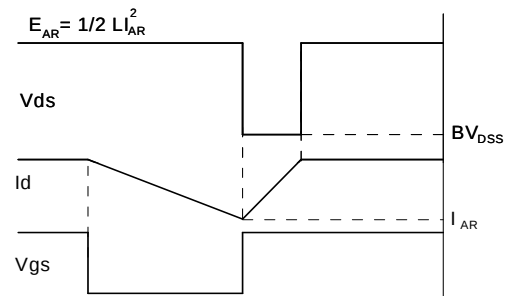
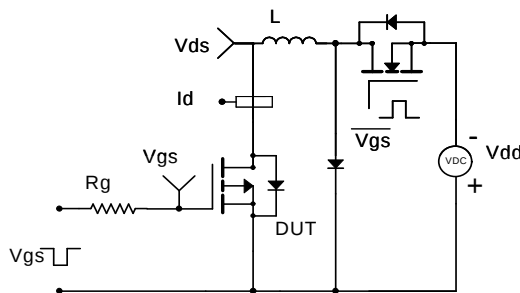
Gate Charge Test Circuit & Waveform



Resistive Switching Test Circuit & Waveforms



Unclamped Inductive Switching (UIS) Test Circuit & Waveforms



Diode Recovery Test Circuit & Waveforms

